



5th Round Table on
M / N – Technologies
for Space
ESTEC

Dr. W. Tschanun MBA

<http://www.reinhardt-microtech.ch>



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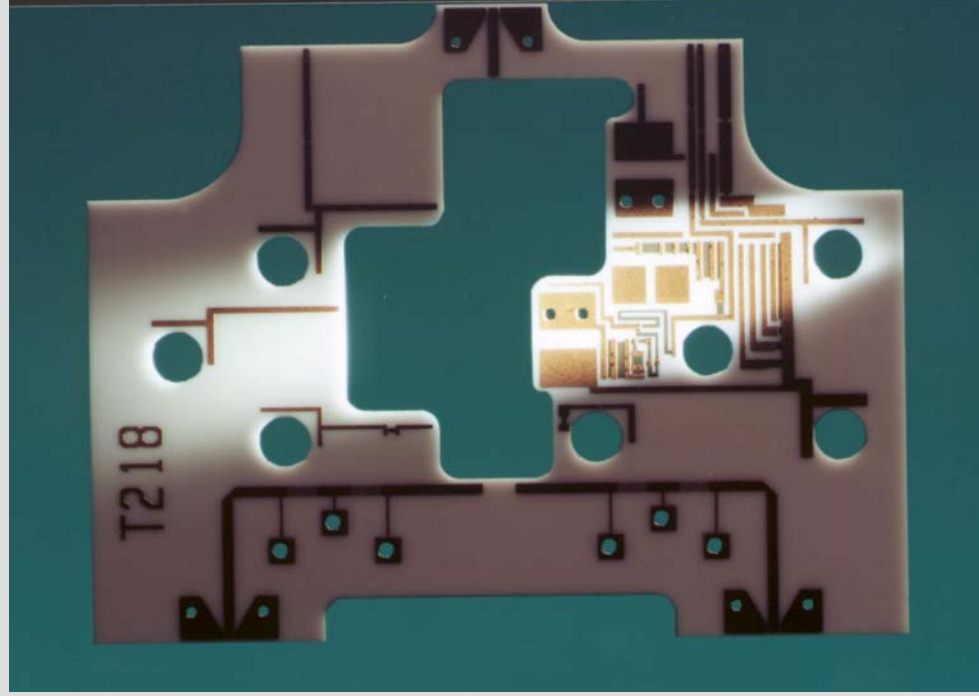
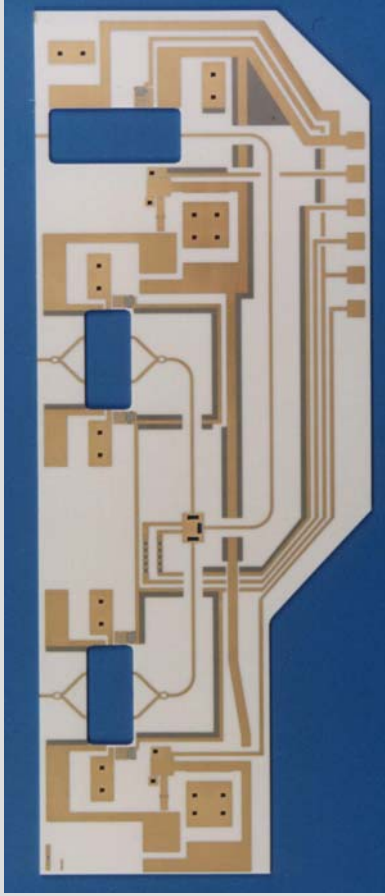
- **who is RMT**
- **what are we doing**
- **our standard products**
- **processes / applications**
- **MST technologies used**
- **RF – MEMS Membrane Filter**
- **packaging concept**
- **concluding remarks**
- **discussion**

mission statement

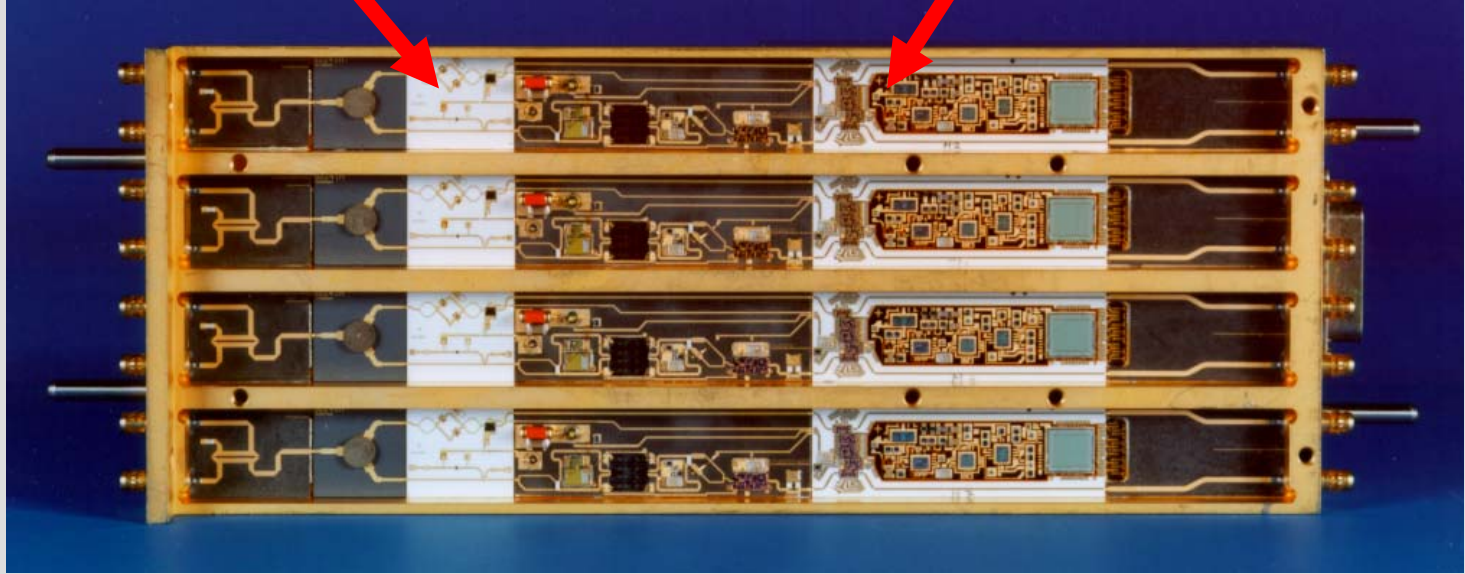
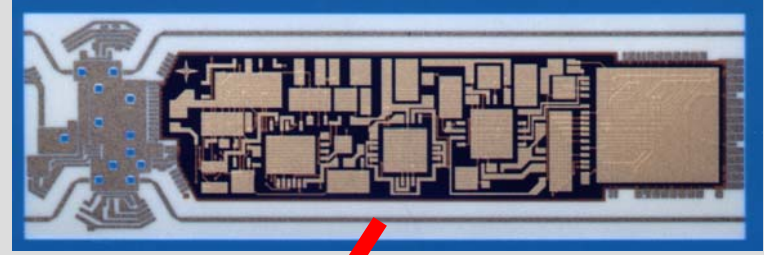
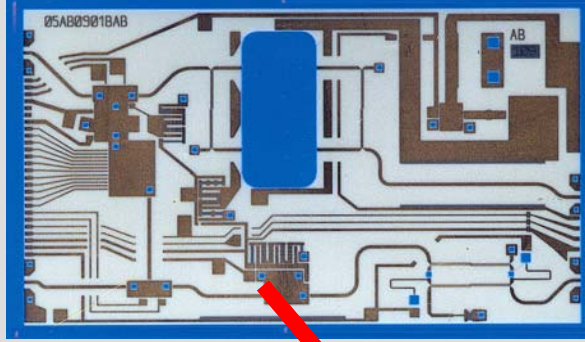
The Reinhardt Microtech Group is worldwide a leading manufacturer of thin film substrates for microelectronics, opto-electronics and highest frequency technology.

The Reinhardt Microtech Group wants to be the European industrial partner for the manufacturing of components in microsystem technology (MST).

thin film products



thin film products



processes available at RMT

such as:

cleaning:	US-bath, brushing, etc. ...
sputtering:	Cr, Ni, Au, Al, Cu, Pd, etc. ...
evaporation:	Sn, Au, ... etc., dielectric
electroplating:	Au, Cu, Ni ...
structures:	6" – masks, 5" – wafer, 4x4" critical dimension > 5µm
wet etching:	Au, Cr, Ni, Al, Si ...
plasma etching:	Si
laser work CO₂:	Al₂O₃, ALN, glass
R- trimming:	active, passive
anodic bonds:	Si, glass
sawing:	Al₂O₃, AlN, glass, etc. ...

sputtering process

substrates: glass, Si-waver, Al_2O_3 etc. up to 6"

layer: Cr, NiCr, Ta_2N , Ni, Ti, TiW, Pd, Au, Al etc.



wet chemical etching resist spinning



areas of application 2004

Reinhardt Microtech Group

telecommunication 16%

antennas
base stations
cable TV
opto-electronics



industry 7%

measurement tools
sensors



medicine 28%

hearing aids
pacemakers



space 3%

satellites
microwave circuits



defence 31%

avionics
radar systems



automotive 10%

GPS
sensors

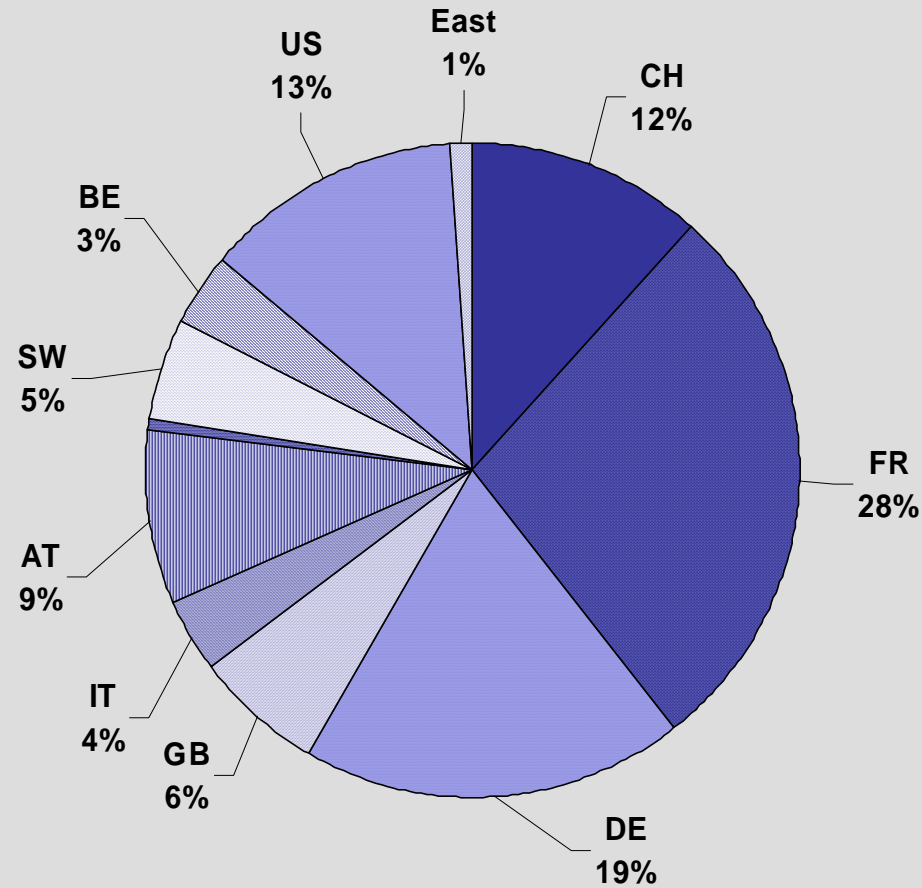


various 5%

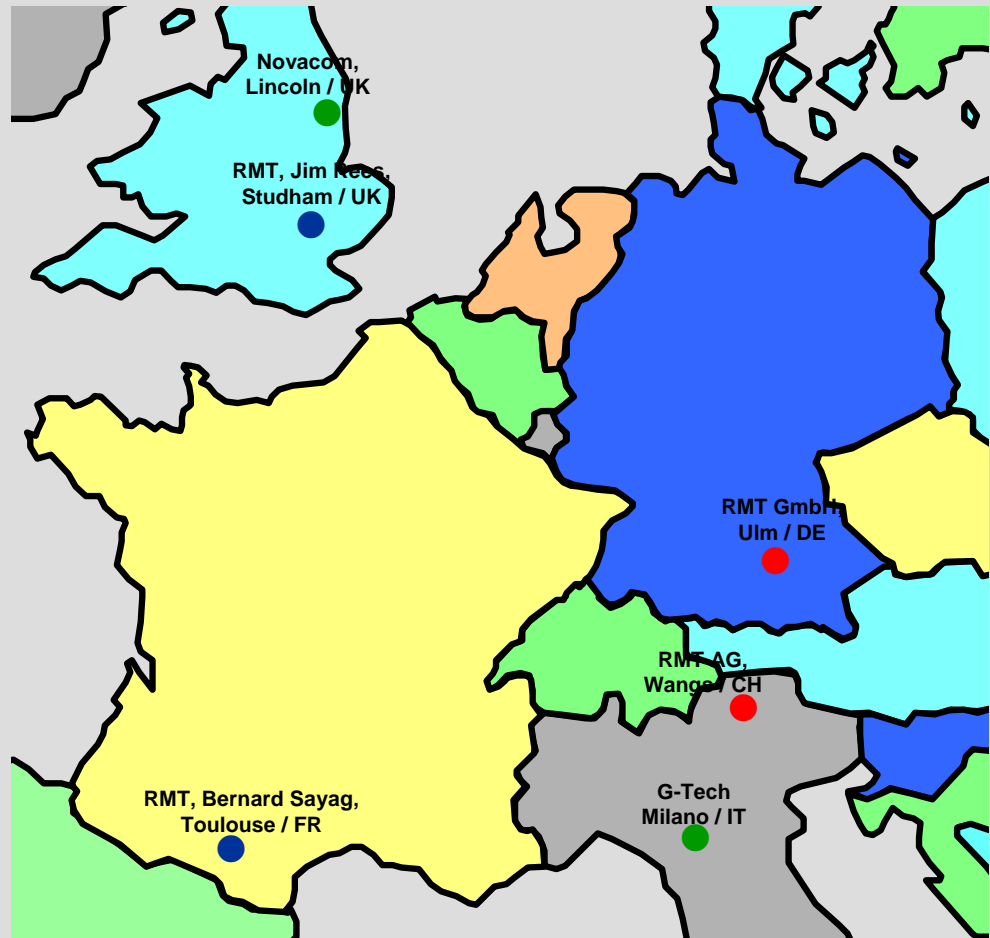
high precision fan outs
MST, Laser work etc.

market 2004

Reinhardt Microtech Group



locations Europe



- manufacturing and sales
- sales offices
- representatives

representative
in Israel:
Emmtech, Gedera
/ Israel

company structure 2005

Reinhardt Microtech Group

- **share capital (privately owned)** : CHF 1'800'000.-
- **company's capital** : EUR 600'000.-

- **number of personnel Wangs & Ulm** : 70

- **personnel structure** : Wangs Ulm

physicist/chemist Dr. (PhD)	:	5	4
bachelor of science Eng.(HTL)	:	4	2
qualified personnel	:	24	13
semi-skilled personnel	:	<u>15</u>	<u>3</u>
		48	22

- **male / female** : 1/3 / 2/3

competence centre Wangs



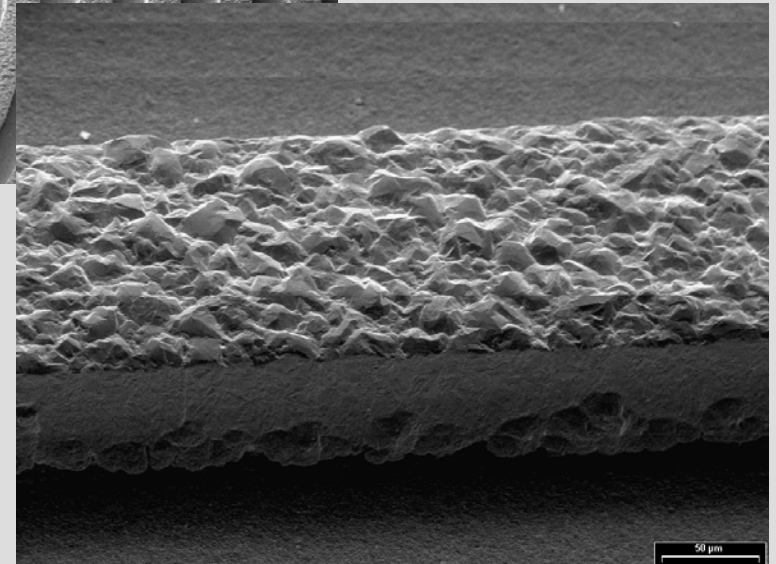
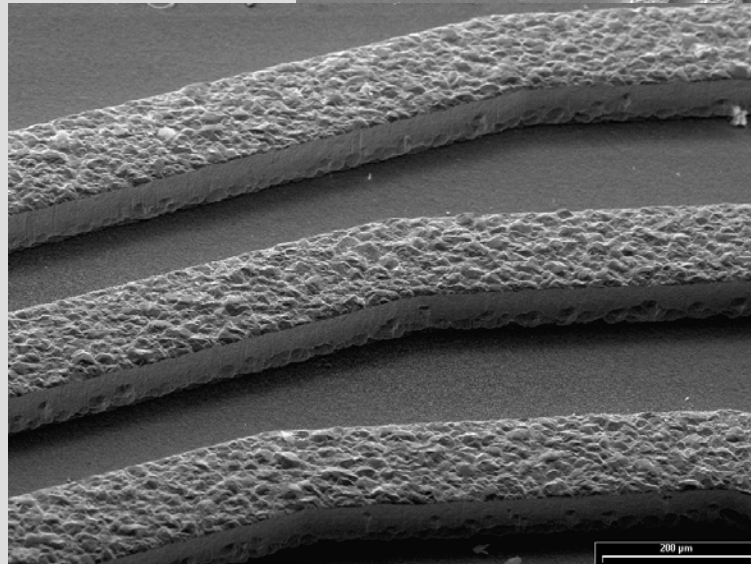
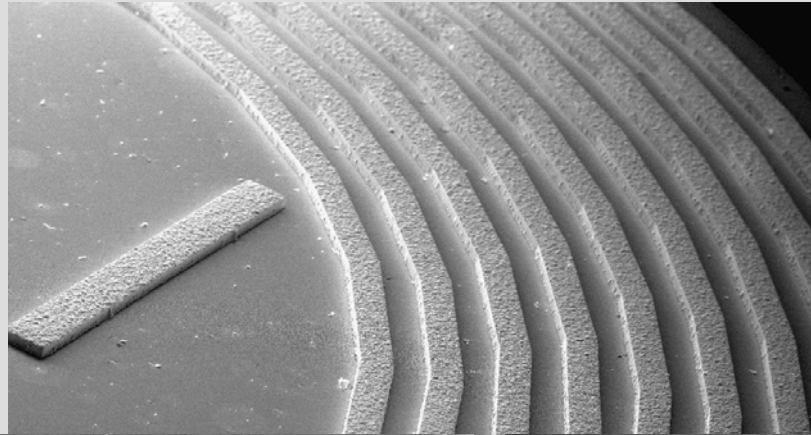
micro coil

substrates: Al_2O_3

layer: TiW + 80 μm Au (elp.)

height: 80 μm

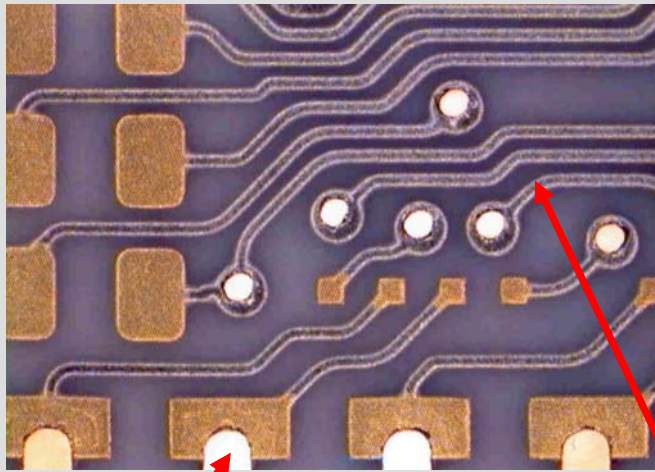
strip line: 120 μm



high density interconnect substrates

- enhanced design rules

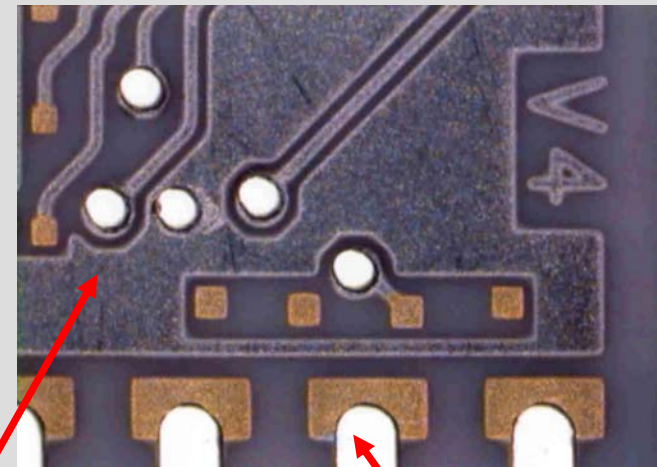
circuit front side



half holes

passivated NiOx

circuit back side

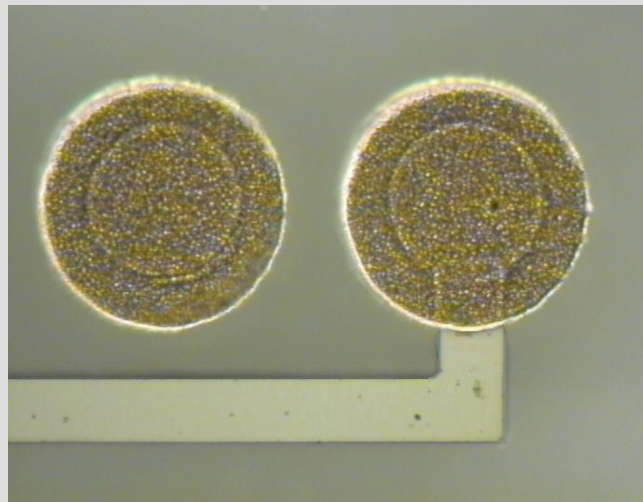


half holes

high density interconnect substrates

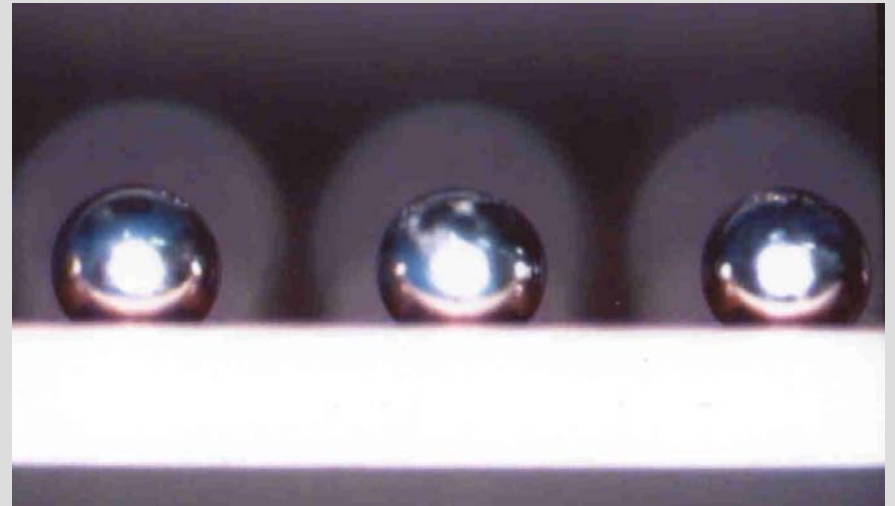
- solder bumps

solder AuSn evp dia. 60 μ m



top view

solder balls PbSn placed dia. 500 μ m

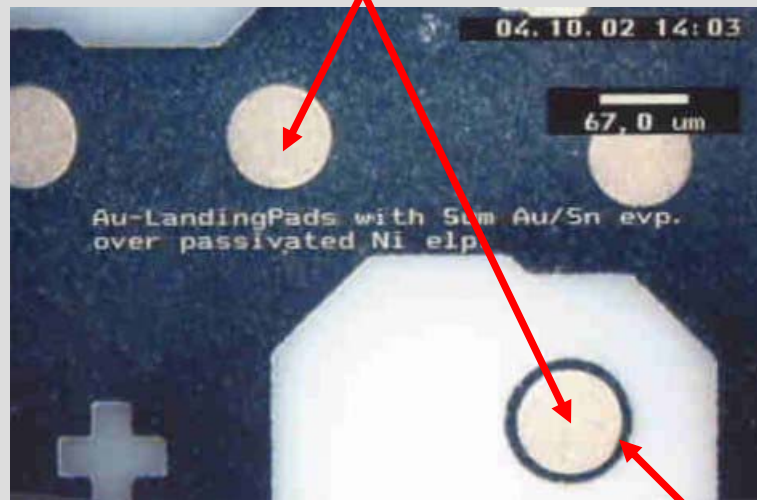


side view

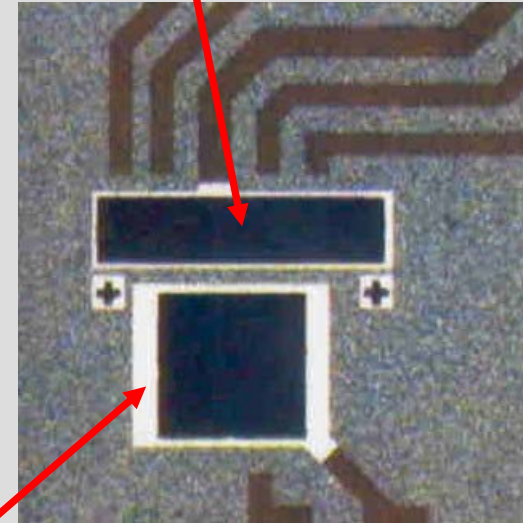
high density interconnect substrates

- solder stop NiOx

solder balls AuSn



solder pads AuSn



solder stop NiOx

high density interconnect substrates

- enhanced bond & solder pads

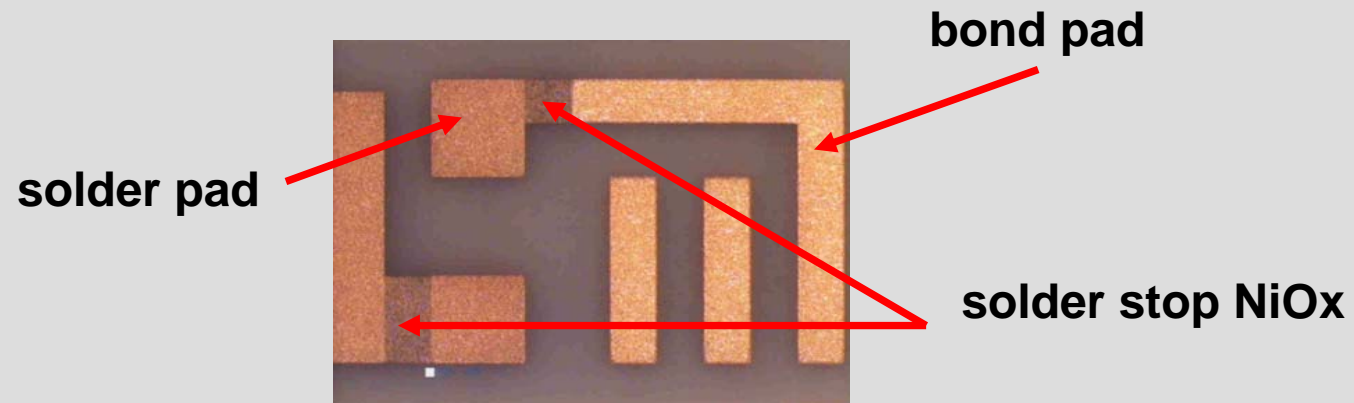
application: high density flip chip substrates, submounts

features: two level gold deposition
enhanced bondability and solderability
for high yield assembly processes

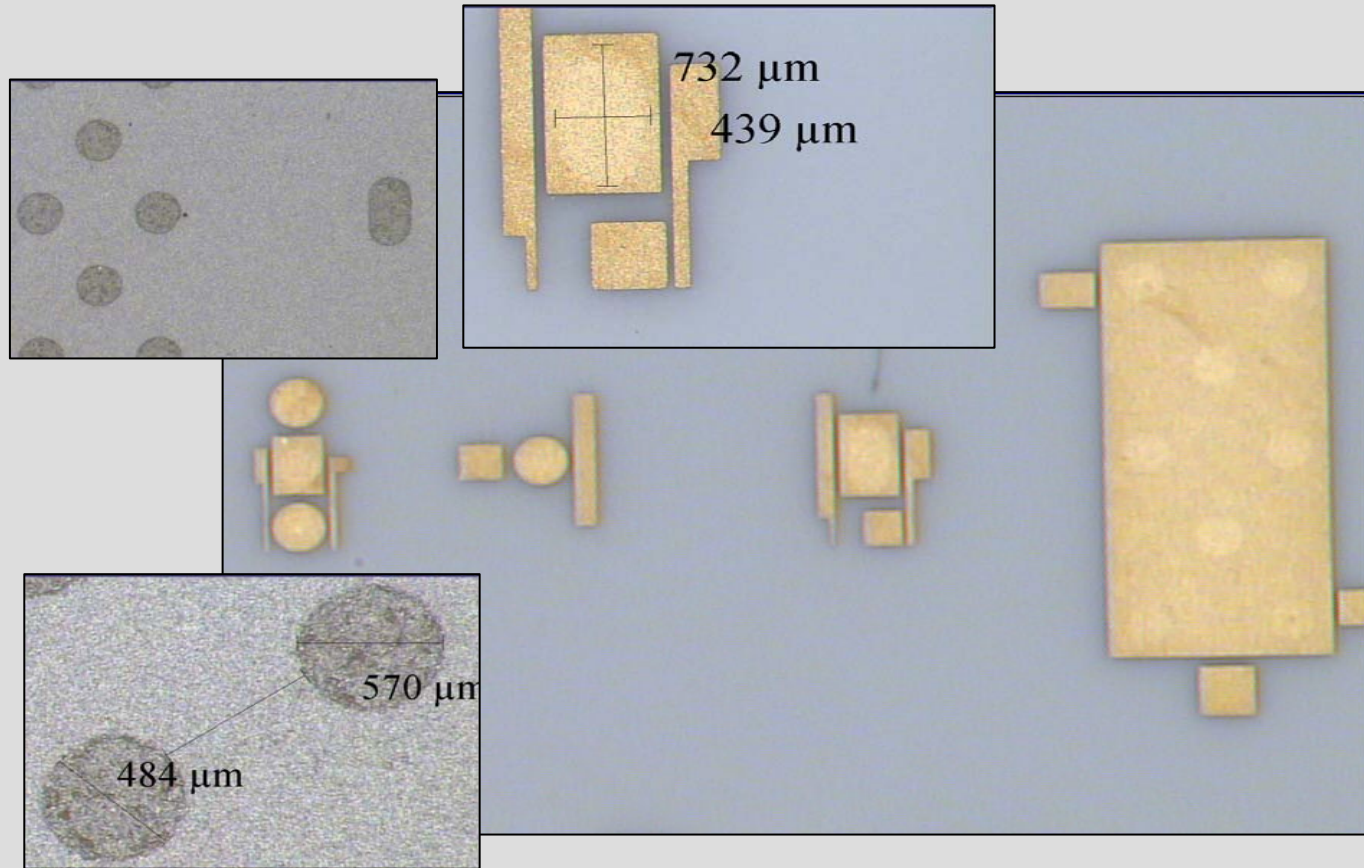
bondability: eg. $2\mu\text{m Au}$

solderability: eg. $0.3 - 0.8\mu\text{m Au}$

solder barrier: Ni, Pd

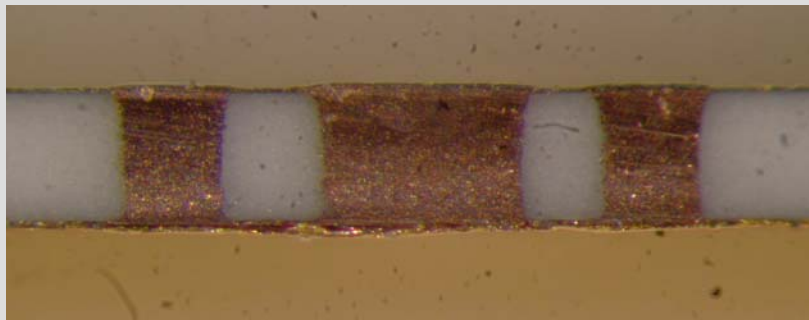


Cu filled via

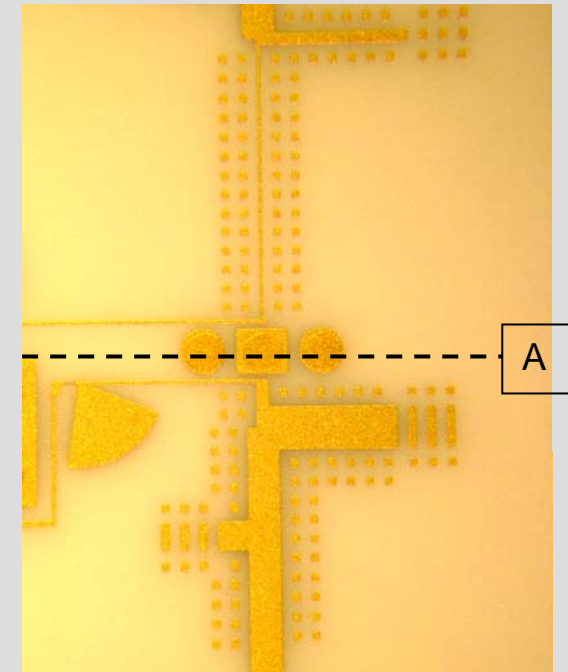


filled via with pure copper

**cut through the filled via
(position A)**

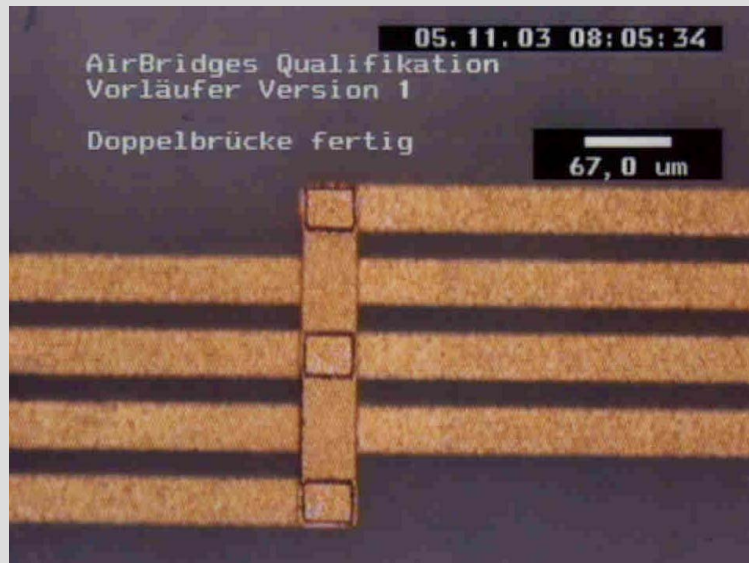


**top view of
substrate showing
section information**

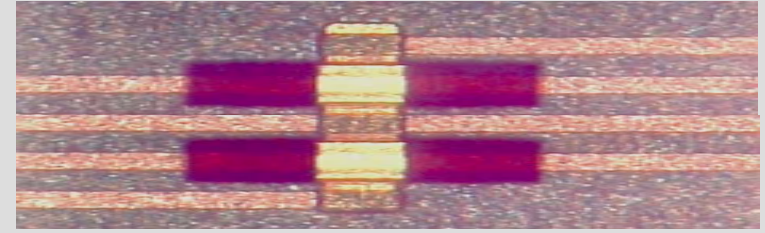
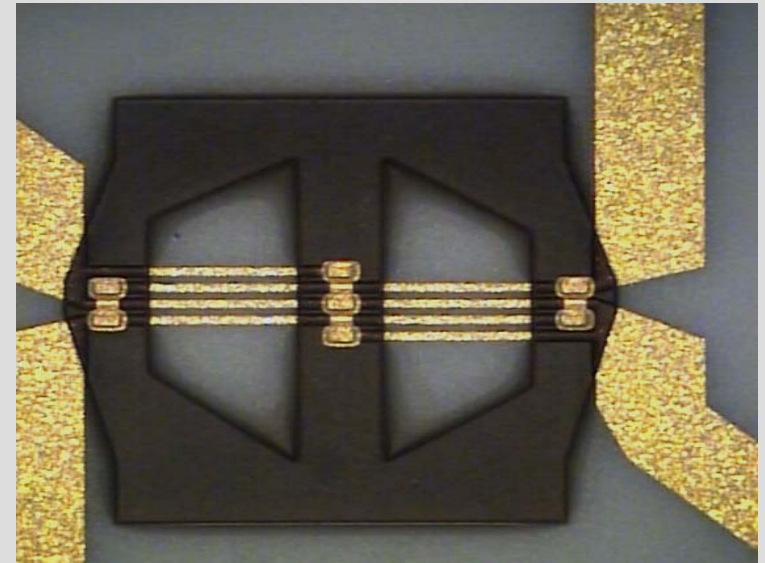


lange coupler with airbridges

cantilever airbridge



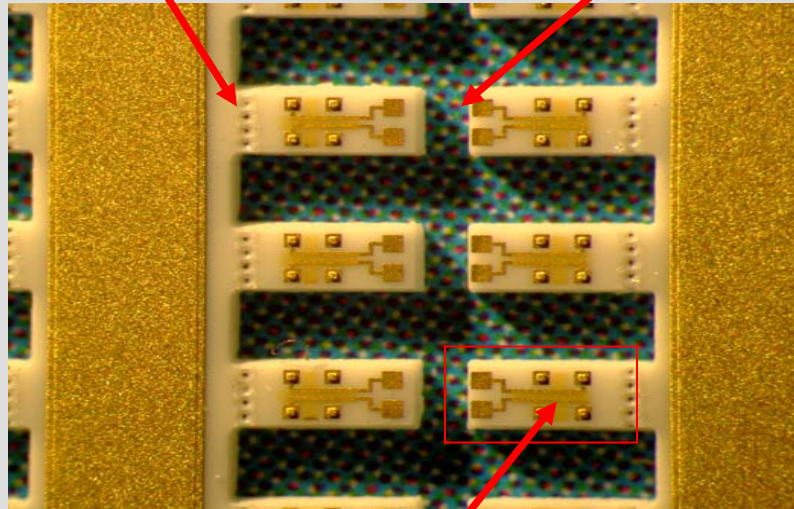
polyimide supported bridge



high precision laser - cut outs

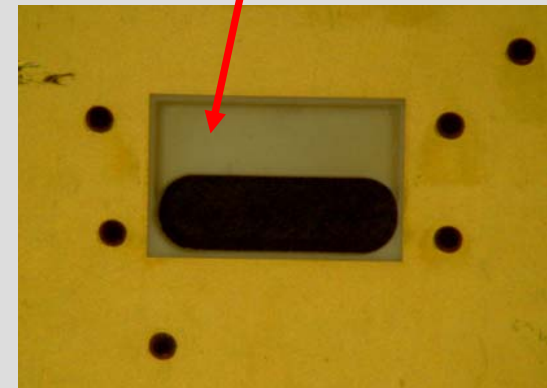
laser scribing

laser cutting



dim.: 1,2 x 0,5 mm

ceramic-cavity



ferrites

- **thickness: 0,25 to 2 mm**
- **surface: polished or as fired**
- **integrated resistors**
- **edge metallisation**
- **through hole metallisation**
- **laser cut and drilled**

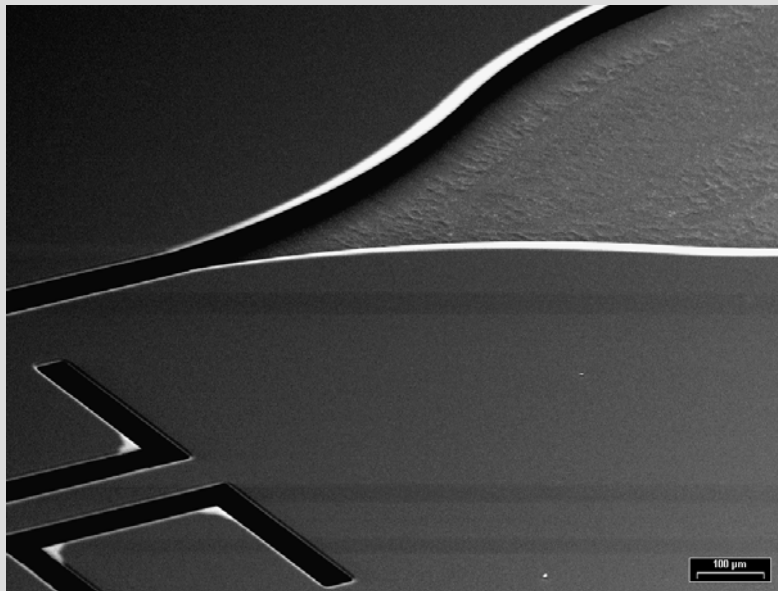


synergies for MST - Technology at RMT

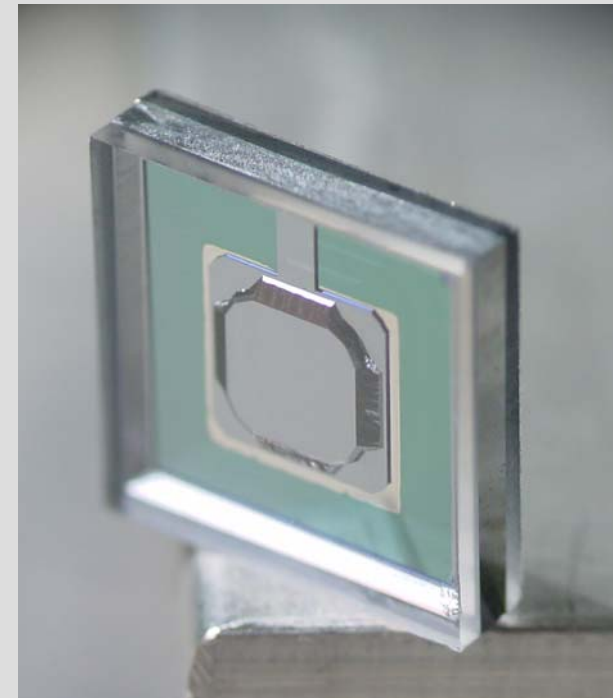
**We use our standard processes to develop and
manufacture MST – Products**

Examples are:

TECAN



FESTO



Developments with the partner NTB / NMT

Why RF - MEMS Membrane Filters at RMT ?

- **We will use our standard technology to diverse into components manufacturing.**
- **Reaction to commercial customer demand**
- **We will use our standard manufacturing processes in a new follow up**
- **We will enlarge our offer to an existing customer base later on**

MST - technology

The Reinhardt Microtech Group is a technology driven company.

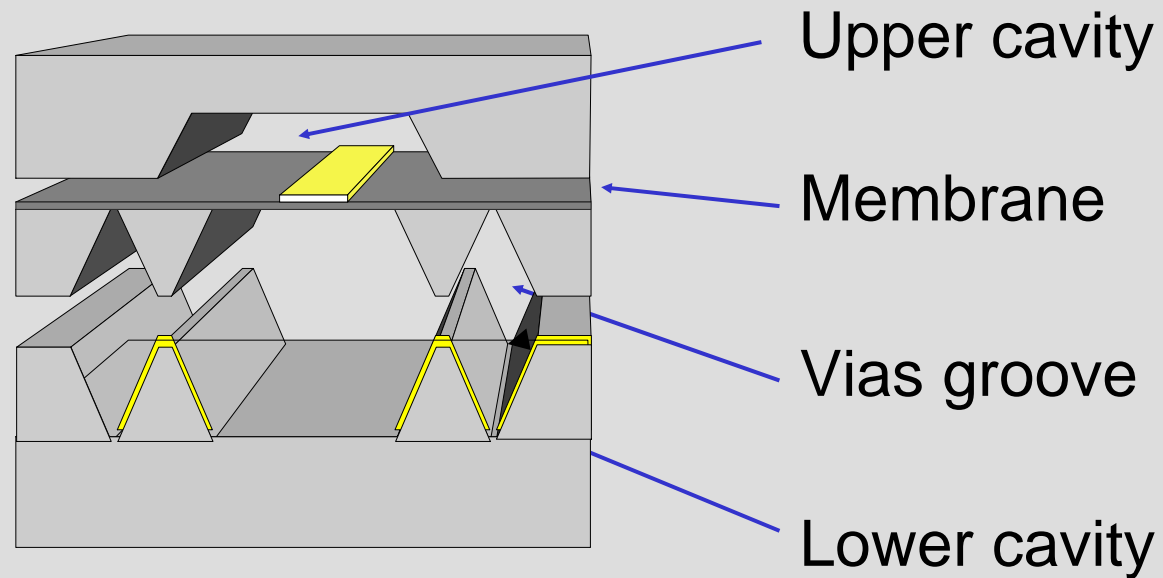
We have a leading position in Europe and are also a partner in several European projects such as:

- **Eureka**
- **Eurimus**
- **Prokosmos (D)**
- **KTI**

RMT sells technology as a service

Rf – MEMS Membrane Filter

Filter Basics



- **novelty: Au coated cavities**

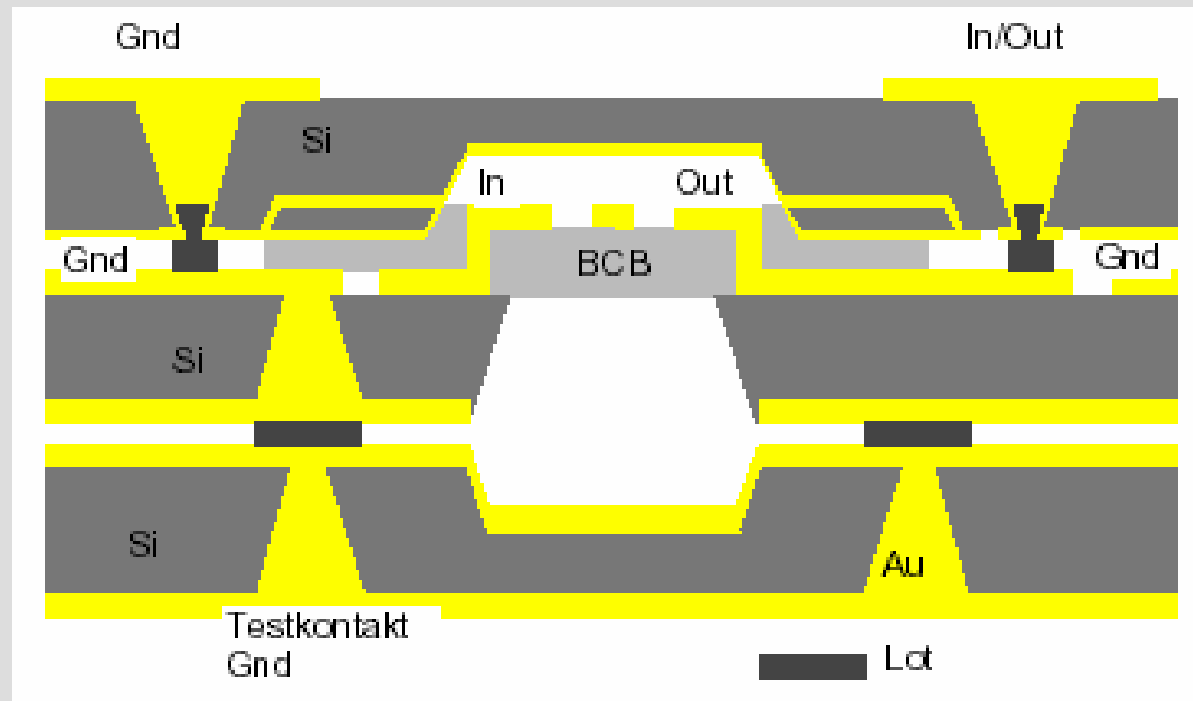
RF – MEMS Membrane Filter

Packaging concept I

- **easy SMT mountable device**
- **simple device test**
- **proper integration to RF – Environments**
- **different levels of Hermeticity**

RF – MEMS Membrane Filter

Packaging concept II



- packaging concept with electroplated vias and soldering interconnections

concluding remarks

- **Project duration end of 2006**
- **First successful steps are performed**
- **Partners included**
 - **ESA**
 - **CNES**
 - **SSO**
 - **a French industrial group**
 - **a French university**